



Product Change Notification

Change Notification #: 116870 - 00
Change Title: Intel® Server Hot-Swap Backplane
FR1304S3HSBP,
PCN 116870-00, Product Design,
Hot-Swap Back Plane Firmware Update
Date of Publication: March 28, 2019

Key Characteristics of the Change:

Product Design

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material: *	April 16, 2019
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* Intel appreciates the customer's desire to receive the latest revision of products. However, Intel manages inventory on a first in first out (FIFO) basis at the MM# level. Subsequently, customer requests for a specific revision of material (below the MM#) will not be supported by Intel.

Description of Change to the Customer:

Intel is updating the Hot-Swap Back Plane (HSBP) firmware to the version 1.41 of the Intel Server Hot-Swap Back Plane listed in the "Products Affected" table below. The firmware version 1.41 fixes a fault LED issue found on manufacturing.

Customer Impact of Change and Recommended Action:

Intel does not expect any other impact to customers from this change, but encourages customers to understand the change and determine the impact on their applications. For that reason Intel recommends that the customer perform a standard level of evaluation. Customers can download and evaluate the latest BIOS/ME/Integrated BMC and FRUSDR release notes for more information at <http://www.intel.com/support>.

Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre Change TA	Post Change TA
FR1304S3HSBP	934887	G98591-006	G98591-007

PCN Revision History:

Date of Revision:	Revision Number:	Reason:
March 28, 2019	00	Originally Published PCN



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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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